

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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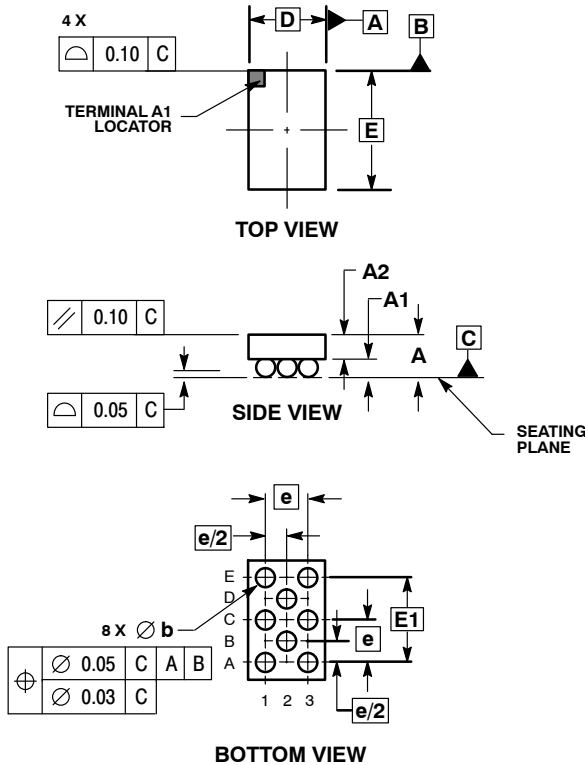


### 8 PIN FLIP-CHIP CASE 499AM-01 ISSUE 0

DATE 17 FEB 2005



SCALE 4:1

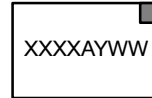


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	1.270 BSC	
E	1.970 BSC	
b	0.290	0.340
e	0.700 BSC	
E1	1.400 BSC	

#### GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G or ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "■", may or may not be present.

<b>DOCUMENT NUMBER:</b>	<b>98AON20414D</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>8 PIN FLIP-CHIP, 1.970*1.270,, 0.700 LEAD PITCH</b>	<b>PAGE 1 OF 1</b>

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